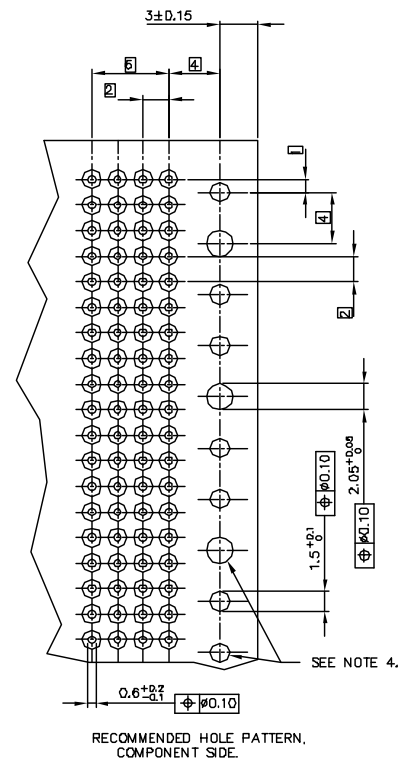
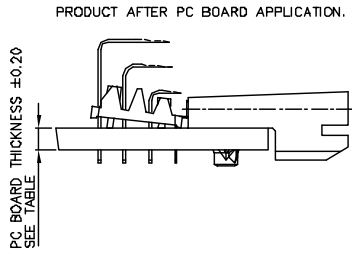
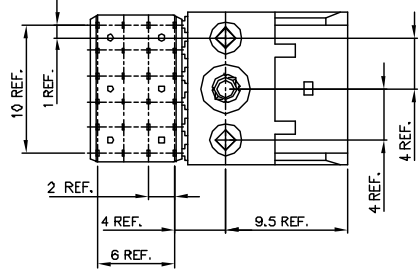
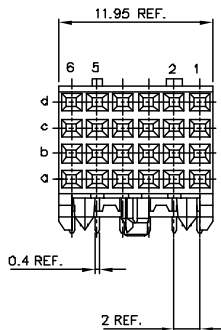
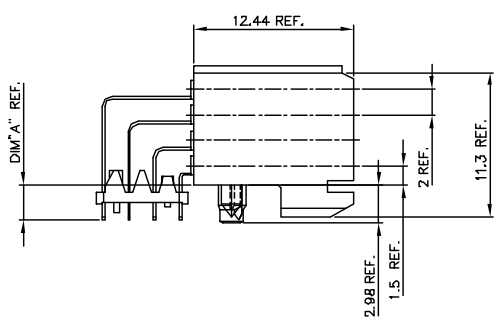


PC BOARD VERSIONS		
PRODUCTNR:	PCB THICKNESS	DIM "A"
89035-X01	1.6	2.73
89035-X11	2.4	3.53
89035-X01LF	1.6	2.73
89035-X11LF	2.4	3.53

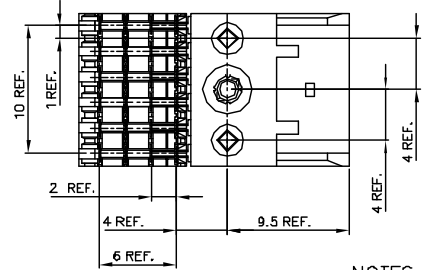
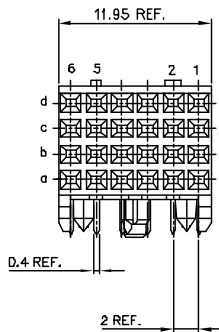
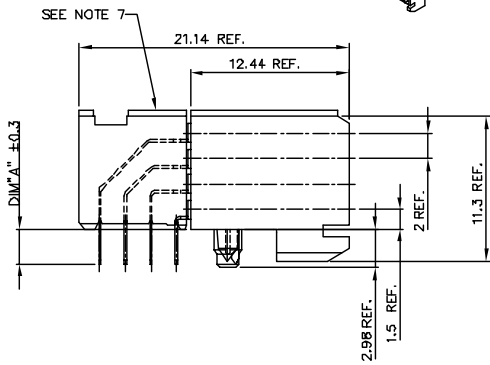
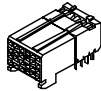


- NOTES:
- BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
 - TERMINAL MATERIAL: PHOSPHOR BRONZE.
 - PLATING SOLDER TAILS 2-8 µm SnPb 90-97 OR 2-8 µm PURE Sn FOR LEAD FREE.
 - INDICATED HOLES ARE UNPLATED.
 - PRODUCT MARKING: PARTNUMBER & BATCH ID.
 - THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-00B.
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
89035-1Y2LF	0.8 µm GOLD	1.3 µm Ni MIN.
89035-2Y2LF	2 µm GOLD	1.3 µm Ni MIN.
89035-3Y2LF	1.3 µm GOLD	1.3 µm Ni MIN.
89035-9Y2LF	0.8 µm GXT	1.3 µm Ni MIN.
89035-1YZ	0.8 µm GOLD	1.3 µm Ni MIN.
89035-2YZ	2 µm GOLD	1.3 µm Ni MIN.
89035-3YZ	1.3 µm GOLD	1.3 µm Ni MIN.
89035-9YZ	0.8 µm GXT	1.3 µm Ni MIN.

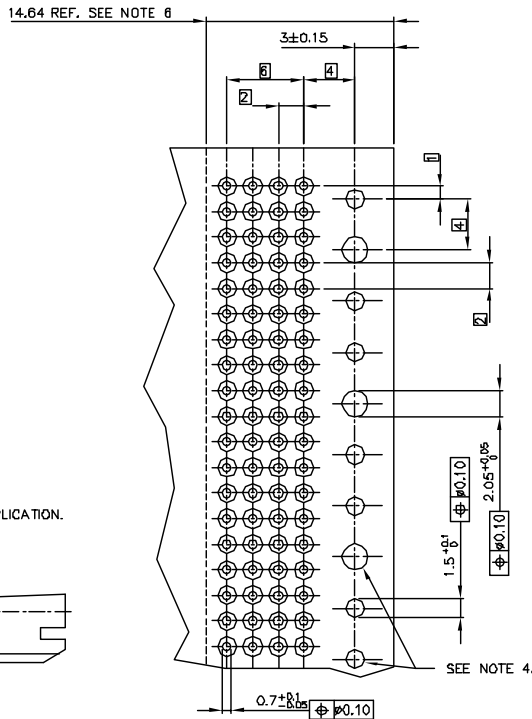
mat'l code		tolerances unless otherwise specified		CUSTOMER COPY		ELECTRONICS	
itr	ser no	date	inour	proj	part	code	213
H	0044-004	041220					
C	146018	07E	040211	angles			
D	146036	000	040307	dr	U	091918	
F	172789	000	070005	0102	0100000001	040201	
G	100078	000	000000	0000	000000	000000	
g	100047	000	000000	0000	000000	000000	
sheet	1	of	1				
index	sheet	1	of	1			

PC BOARD VERSIONS		
PRODUCT NR.	PCB THICKNESS	DIM 'A'
89035-X02	1.6	2.73
89035-X12	2.4	3.53
89035-X02LF	1.6	2.73
89035-X12LF	2.4	3.53



PRODUCT AFTER PC BOARD APPLICATION.

PC BOARD THICKNESS ±0.20
SEE TABLE



NOTES:

- BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
- TERMINAL MATERIAL: PHOSPHOR BRONZE.
- PLATING SOLDER TAILS 2-8 µm SnPb 90-97 OR 2-8 µm PURE Sn
- INDICATED HOLES ARE UNPLATED.
- PRODUCT MARKING: PART NUMBER & BATCH ID.
- SET BACK FOR PRESS BLOCK.
- TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO 0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE TAIL LENGTH BEFORE APPLICATION TO A BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN CS-22-008.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR.	PLATING CONTACT AREA	UNDERPLATING
89035-1Y2LF	0.8 µm GOLD	1.3 µm Ni MIN.
89035-2Y2LF	2 µm GOLD	1.3 µm Ni MIN.
89035-3Y2LF	1.3 µm GOLD	1.3 µm Ni MIN.
89035-9Y2LF	0.8 µm GXT	1.3 µm Ni MIN.
89035-1Y2	0.8 µm GOLD	1.3 µm Ni MIN.
89035-2Y2	2 µm GOLD	1.3 µm Ni MIN.
89035-3Y2	1.3 µm GOLD	1.3 µm Ni MIN.
89035-9Y2	0.8 µm GXT	1.3 µm Ni MIN.

mat'l code		tolerances unless otherwise specified		CUSTOMER COPY		ELECTRONICS	
itr	san no	date	linear	projection	first	code	RA FEMALE SIGNAL
H			angles	1st	12 mm PRESS PEG	213	
			dr. n. de m	mm	product	sheet	
			eng. n. schen	070509	terminal	2 of	
			chf. n. schen	070509	TRAIL (m)		
			chf. n. schen	070509	scale		
			0509	070509	1:1		
sheet	revision						
index	sheet						